

FEATURES

- **HIGH POWER**
P1dB=36.5dBm at 14.0GHz to 14.5GHz
- **HIGH GAIN**
G1dB=6.5dB at 14.0GHz to 14.5GHz
- **BROAD BAND INTERNALLY MATCHED FET**
- **HERMETICALLY SEALED PACKAGE**

RF PERFORMANCE SPECIFICATIONS (Ta= 25°C)

| CHARACTERISTICS | SYMBOL | CONDITIONS | UNIT | MIN. | TYP. | MAX. |
|--|--------|--|------|------|------|------|
| Output Power at 1dB Gain Compression Point | P1dB | VDS= 9V f= 14.0 to 14.5GHz | dBm | 36.0 | 36.5 | — |
| Power Gain at 1dB Gain Compression Point | G1dB | | dB | 6.0 | 6.5 | — |
| Drain Current | IDS1 | | A | — | 1.7 | 2.2 |
| Gain Flatness | ΔG | | dB | — | — | ±0.8 |
| Power Added Efficiency | ηadd | | % | — | 23 | — |
| 3 rd Order Intermodulation Distortion | IM3 | Two-Tone Test Po=25.0 dBm | dBc | -42 | -45 | — |
| Drain Current | IDS2 | (Single Carrier Level) | A | — | 1.7 | 2.2 |
| Channel Temperature Rise | ΔTch | (VDS X IDS + Pin - P1dB) X Rth(c-c) | °C | — | — | 60 |

Recommended Gate Resistance(Rg): 150 Ω (Max.)

ELECTRICAL CHARACTERISTICS (Ta= 25°C)

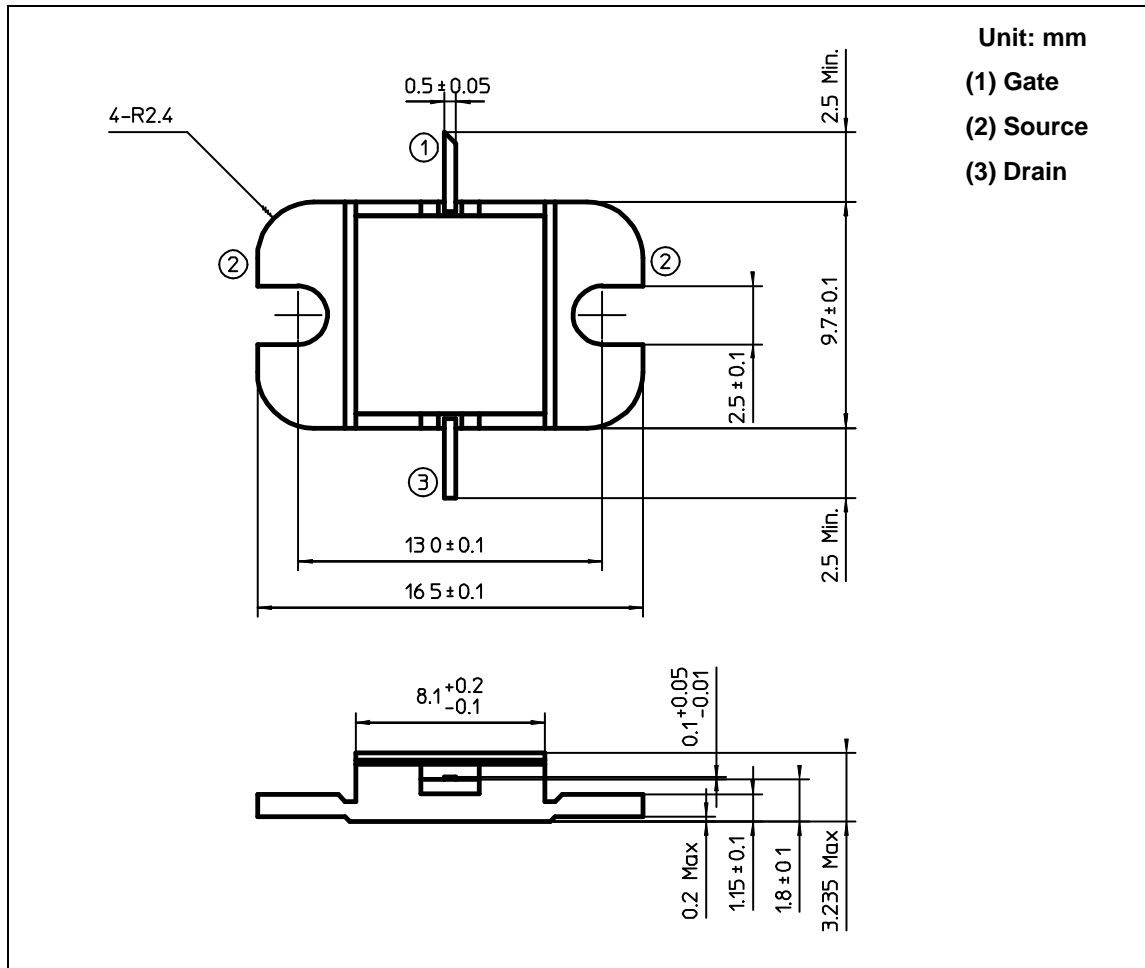
| CHARACTERISTICS | SYMBOL | CONDITIONS | UNIT | MIN. | TYP. | MAX. |
|-------------------------------|----------|----------------------|------|------|------|------|
| Transconductance | gm | VDS= 3V IDS= 2.0A | mS | — | 1200 | — |
| Pinch-off Voltage | VGSoff | VDS= 3V IDS= 60mA | V | -2.0 | -3.5 | -5.0 |
| Saturated Drain Current | IDSS | VDS= 3V VGS= 0V | A | — | 4.0 | — |
| Gate-Source Breakdown Voltage | VGSO | IGS= -60μA | V | -5 | — | — |
| Thermal Resistance | Rth(c-c) | Channel to Case | °C/W | — | 2.9 | 3.5 |

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ABSOLUTE MAXIMUM RATINGS (Ta= 25°C)

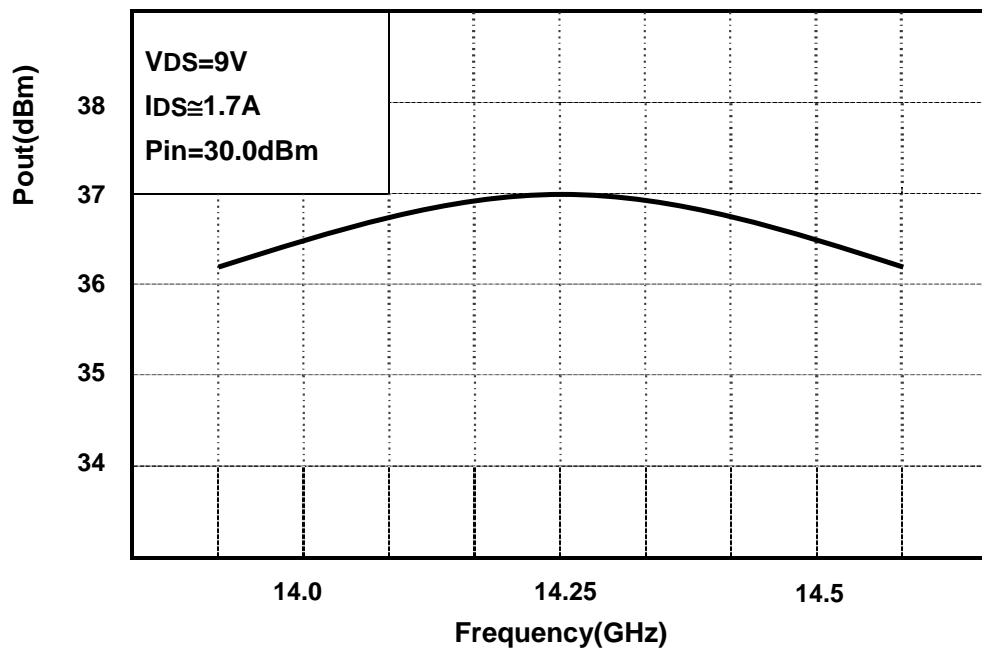
| CHARACTERISTICS | SYMBOL | UNIT | RATING |
|-------------------------------------|--------|------|-------------|
| Drain-Source Voltage | VDS | V | 15 |
| Gate-Source Voltage | VGS | V | -5 |
| Drain Current | IDS | A | 5.2 |
| Total Power Dissipation (Tc= 25 °C) | PT | W | 42.8 |
| Channel Temperature | Tch | °C | 175 |
| Storage Temperature | Tstg | °C | -65 to +175 |

PACKAGE OUTLINE (2-9D1B)**HANDLING PRECAUTIONS FOR PACKAGE MODEL**

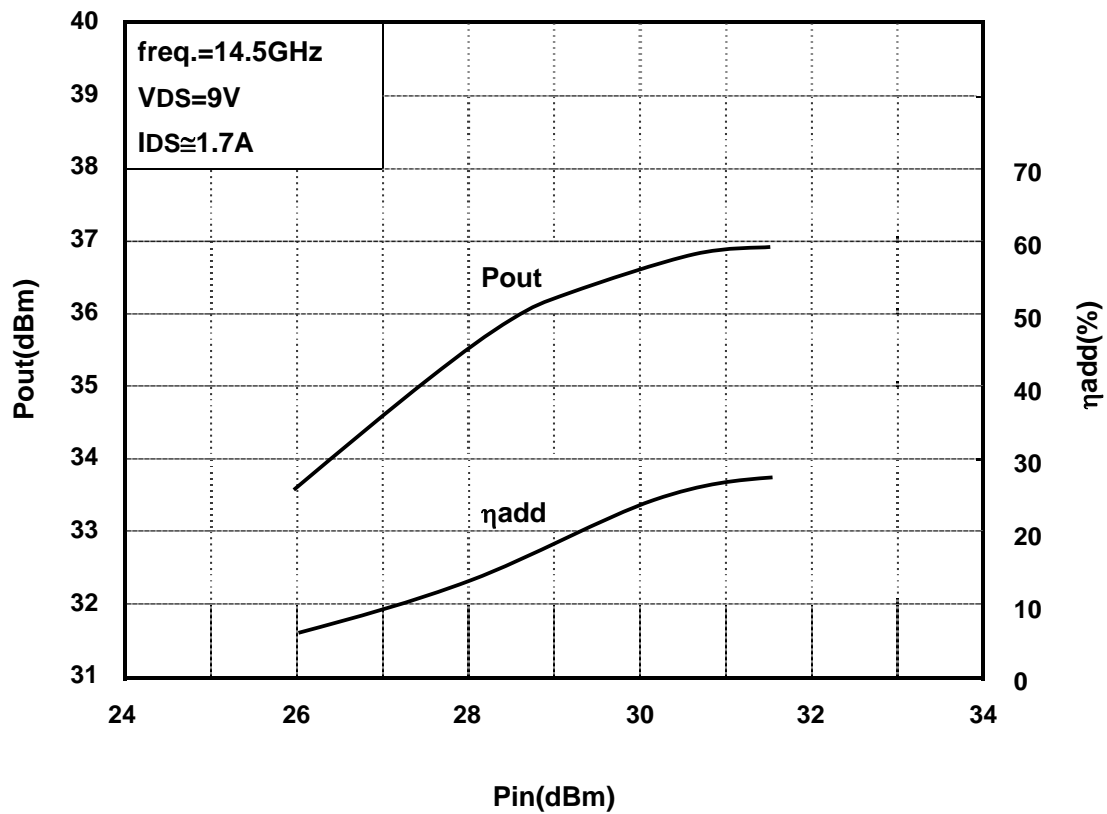
Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

RF PERFORMANCE

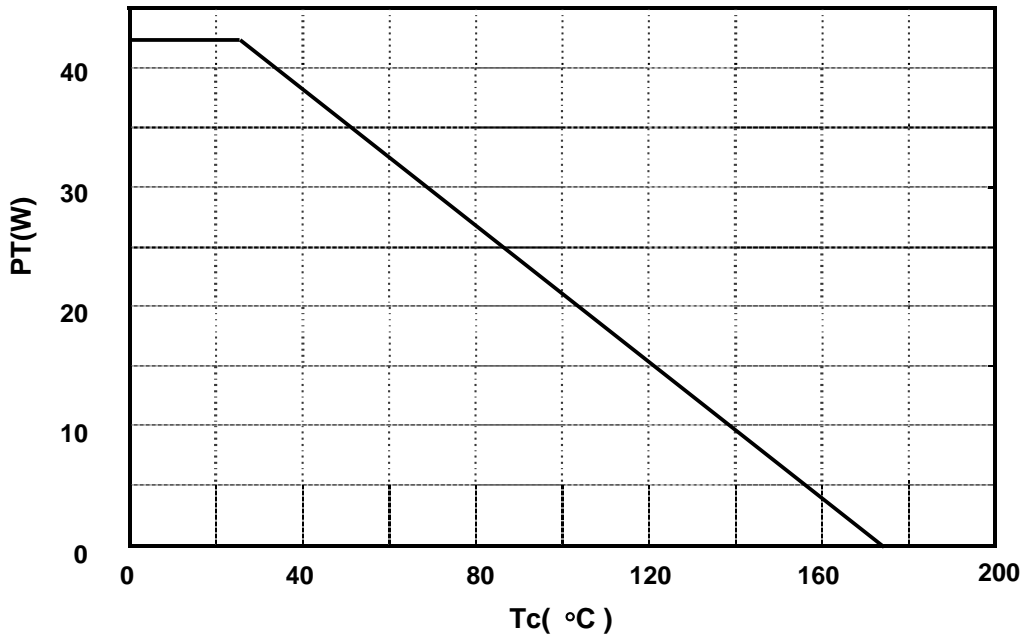
Output Power (Pout) vs. Frequency



Output Power(Pout) vs. Input Power(Pin)



Power Dissipation(PT) vs. Case Temperature(Tc)



IM3 vs. OUTPUT POWER CHARACTERISTICS

